



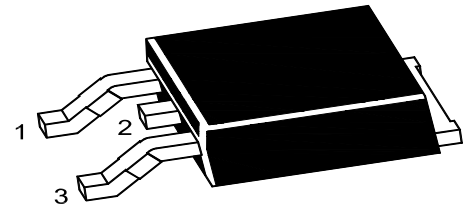
# PJM10H80NTE

## N-Channel Enhancement Mode Power MOSFET

### Features

- Excellent package for good heat dissipation
- High density cell design for ultra low  $R_{DS(on)}$
- $V_{DS} = 100V, I_D = 80A$   
 $R_{DS(on)} < 8.5m\Omega @ V_{GS} = 10V$

TO-252

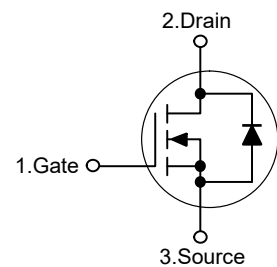


1. Gate 2.Drain 3.Source

### Applications

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

### Schematic Diagram



### Absolute Maximum Ratings

Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	80	A
Drain Current-Pulsed <sup>Note1</sup>	$I_{DM}$	320	A
Single pulse avalanche energy <sup>Note4</sup>	$E_{AS}$	320	mJ
Maximum Power Dissipation	$P_D$	125	W
Junction Temperature	$T_J$	175	°C
Storage Temperature Range	$T_{STG}$	-55 to +175	°C

### Thermal Characteristics

Maximum Junction-to-Case <sup>Note2</sup>	$R_{\theta JC}$	1.25	°C/W
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### Electrical Characteristics

(Ta=25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	100	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=100V, V_{GS}=0V$	--	--	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	--	--	$\pm 0.1$	$\mu A$
Gate Threshold Voltage <sup>Note3</sup>	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.7	2.5	V
Drain-Source On-Resistance <sup>Note3</sup>	$R_{DS(on)}$	$V_{GS}=10V, I_D=40A$	--	7.2	8.5	m $\Omega$
Forward Transconductance <sup>Note3</sup>	$g_{FS}$	$V_{DS}=10V, I_D=40A$	40	--	--	S
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{DS}=50V, V_{GS}=0V, f=1MHz$	--	4200	--	pF
Output Capacitance	$C_{oss}$		--	354	--	pF
Reverse Transfer Capacitance	$C_{rss}$		--	23	--	pF
<b>Switching Characteristics</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=50V, V_{GS}=10V, I_D=40A$ $R_G=4.7\Omega$	--	15	--	nS
Turn-on Rise Time	$t_r$		--	10	--	nS
Turn-off Delay Time	$t_{d(off)}$		--	41	--	nS
Turn-off Fall Time	$t_f$		--	6	--	nS
Total Gate Charge	$Q_g$	$V_{DD}=50V, V_{GS}=10V, I_D=40A$	--	65	--	nC
Gate-Source Charge	$Q_{gs}$		--	15.3	--	nC
Gate-Drain Charge	$Q_{gd}$		--	9	--	nC
<b>Source-Drain Diode Characteristics</b>						
Diode Forward Voltage <sup>Note3</sup>	$V_{SD}$	$V_{GS}=0V, I_S=80A$	--	--	1.2	V
Diode Forward Current <sup>Note2</sup>	$I_S$		--	--	80	A

Note: 1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.

3. Pulse Test: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$

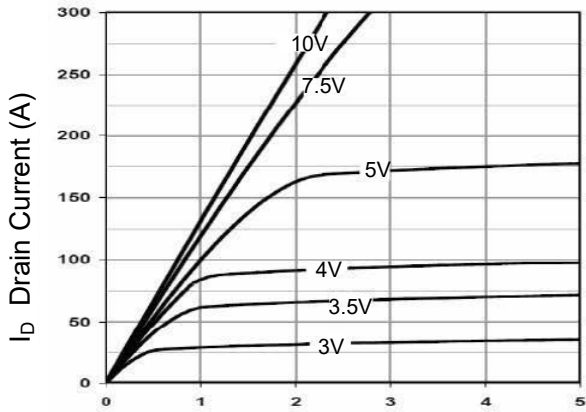
4.  $E_{AS}$  condition :  $T_j=25^\circ C, V_{DD}=50V, V_G=10V, L=0.5mH, R_G=25\Omega$



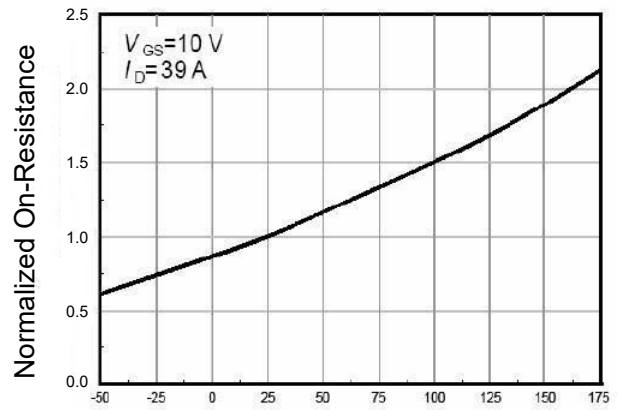
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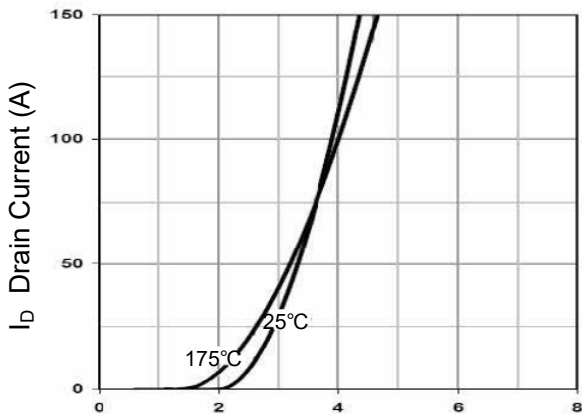
### Typical Characteristic Curves



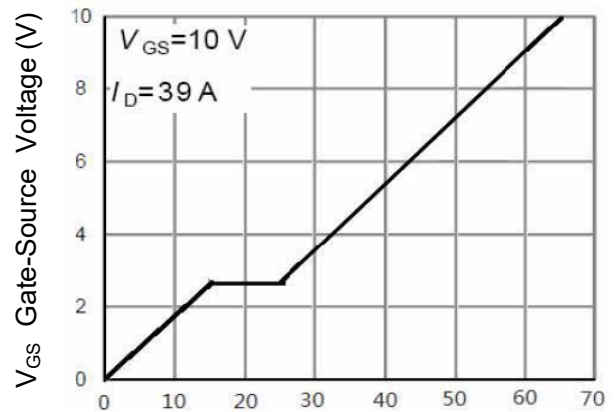
$V_{DS}$  Drain-Source Voltage (V)



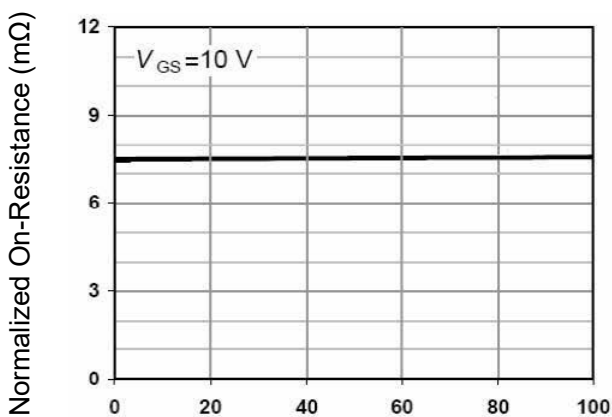
$T_J$  Junction Temperature (°C)



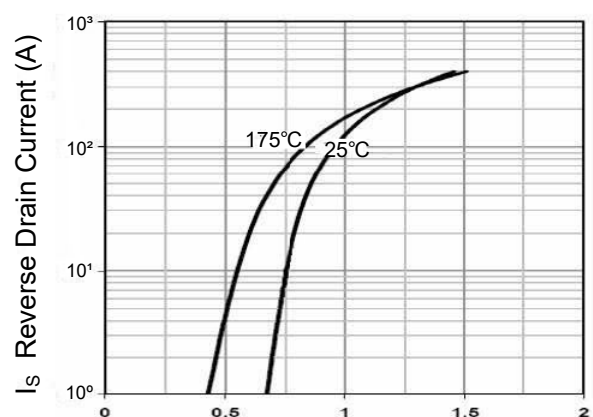
$V_{GS}$  Gate-Source Voltage (V)



$Q_g$  Gate Charge (nC)



$I_D$  Drain Current (A)

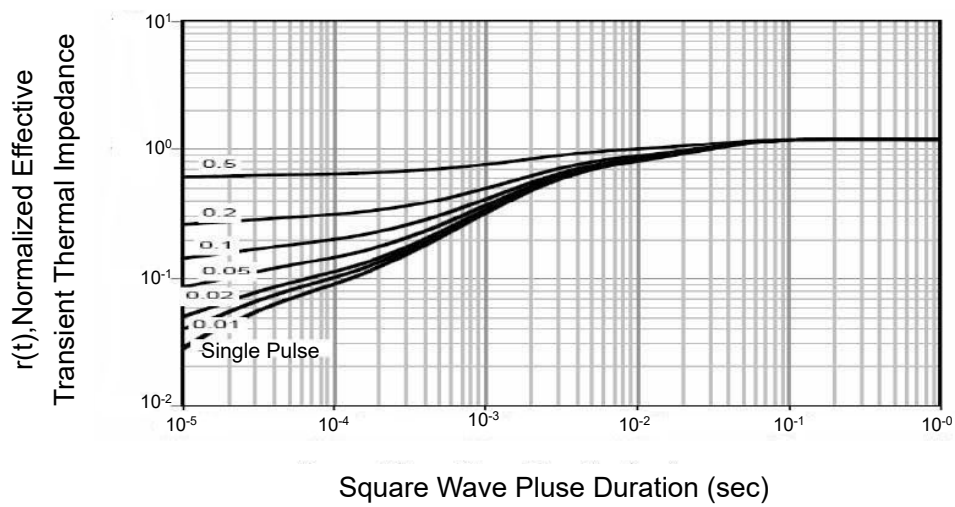
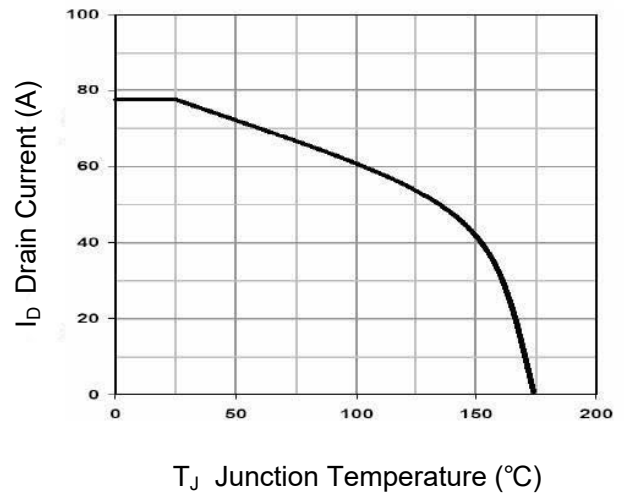
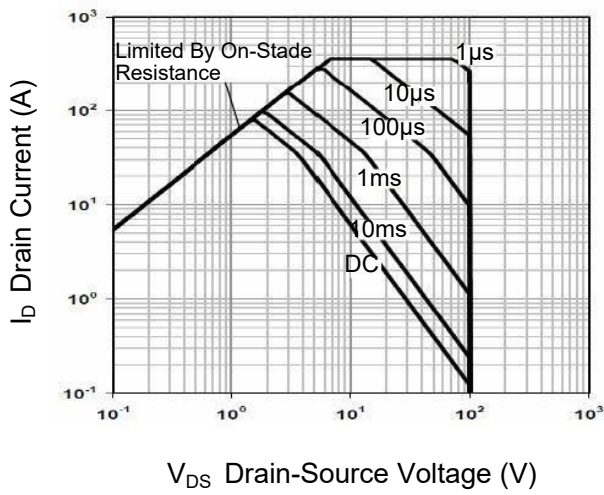
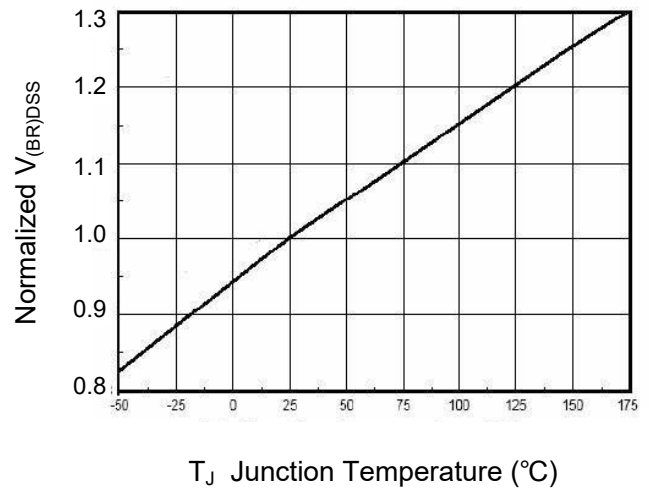
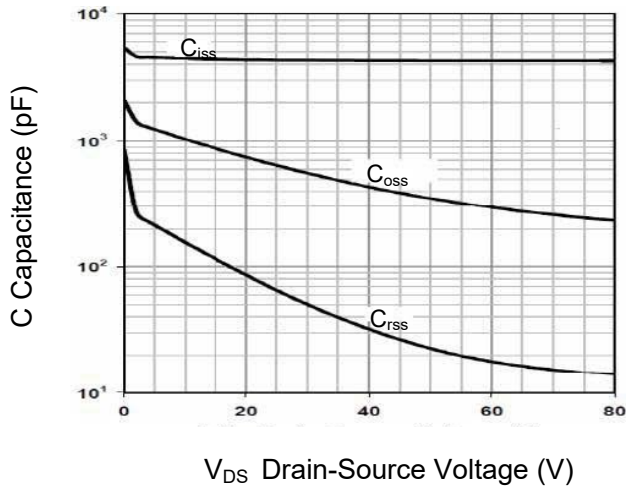


$V_{SD}$  Source-Drain Voltage (V)



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### Package Outline

TO-252

Dimensions in mm

